



Sheet 1 of 1

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INFORMATION DISCLOSURE STATEMENT

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APPLICANT(S): Barstad et al.

FILING DATE:

May 17, 1999

ART UNIT:

1741

UNITED STATES PATENT DOCUMENTS

| EXAM. INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | FIL. DATE IF APPR |
|------------------|----|--------------------|----------|-------------------|-------|--------------|-------------------------|
| W. | AA | 3,876,513 | 04/08/75 | Brown et al. | | | |
| | AB | 4,098,656 | 07/04/78 | Deuber | | | |
| | AC | 4,530,741 | 07/23/85 | Rosenberg | | | |
| | AD | 4,913,787 | 04/03/90 | Kiso | | | |
| | AE | 5,051,154 | 09/24/91 | Bernards et al. | | | |
| | AF | 5,068,013 | 11/26/91 | Bernards et al. | | | |
| | AG | 5,174,886 | 12/29/92 | King et al. | | | |
| | AH | 5,223,118 | 06/29/93 | Sonnenberg et al. | | | |
| | AJ | 5,858,870 | 01/12/99 | Zheng et al. | | | |
| | AK | 5,433,840 | 07/95 | Dahms et al. | | | |
| | AL | 2,424,887 | 07/47 | Henricks | | | |
| W. | AM | 5,151,170 | 09/92 | Montgomery et al. | | | |
| | AN | 4,347,108 | 08/82 | Willis | | | |
| W. | AO | 4,336,114 | 06/82 | Mayer et al. | | | |
| | AP | 4,036,710 | 07/77 | Kardos et al. | | | |
| | AQ | 6,113,771 | 09/00 | Landau et al. | | | |
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| W. | AT | 6,024,857 | 02/00 | Reid | | | |

COPY OF PAPERS
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OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

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|----|----|--|
| W. | BA | Shipley Advance Interconnect, Advanced Interconnect Materials, "Nanoplate" Copper Plating Electrolyte Optimized for 200 nm, Bottom-up Trench Fill" Shipley Company, L.L.C. data sheet. Date not known. |
|----|----|--|

Examiner:

W. J. A. R.

Date:

8/27/02